



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Hui et al.

**Serial No.:** 09/916,197

**Filed:** July 27, 2001

**For:** METHOD FOR ENCAPSULATING INTERMEDIATE CONDUCTIVE ELEMENTS CONNECTING A SEMICONDUCTOR DIE TO A SUBSTRATE AND SEMICONDUCTOR DEVICES SO PACKAGED

**Confirmation No.:** 7070

**Examiner:** J. Vigushin

**Group Art Unit:** 2827

**Attorney Docket No.:** 2269-4712US  
(99-1054.00/US)

**Notice of Allowance Mailed:**

October 29, 2003

**Express Mail Mailing Label No.:** EV 326923561 US

**Date of Deposit with USPS:** January 20, 2004

**Person making Deposit:** Christopher Haughton

*OK to Enter - Ben John S. Vigushin  
05/04/04*

**AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)**

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